
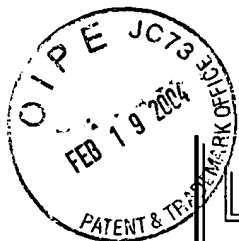


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	Integrated Lead Suspension for High Density Drive						
Application Number: 09/676216							
Confirmation Number: 1147							
First Named Applicant: Tzong-Shii Pan							
Attorney Docket Number:							
Art Unit: 2653							
Examiner: Angel A. Castro							
Search string: (6137657 or 6181525 or 6266212 or 6233121 or 6320729 or 6367145 or 6426851 or 6538850 or 6611402 or 20020051324 or 20020075602).pn.							
		RECEIVED FEB 23 2004 Technology Center 2600					
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6137657	2000-10-24	Coon, et al.			
	2	6181525	2001-01-30	Carlson			
	3	6266212	2001-07-24	Coon			
	4	6233121	2001-05-15	Pan			
	5	6320729	2001-11-20	Coon			
	6	6367145	2002-04-09	Coon			
	7	6426851	2002-07-30	Perez			
	8	6538850	2003-03-25	Hadian, et al.			
	9	6611402	2003-08-26	Mangold			
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020051324	2002-05-02	Nojima			



	2	20020075602	2002-06-20	Mangold, et al.
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Remarks

Note: Remarks are not for responding to an office action.

The U.S. Patent references noted in this Electronic Information Disclosure Statement were cited along with foreign references in a recent office action in copending application serial no. 10/057,639. On Feb. 18, 2004, Applicant submitted by mail an Information Disclosure Statement with form PTO-1449, citing only the foreign references, along with the fee payment required under 37 CFR 1.17(p). On the same day, Applicant tried to concurrently submit the present Electronic Information Disclosure Statement, but due to technical difficulties with online filing, we were not able to complete the filing on the same day. However, the hardcopy filing had already been mailed. Applicant respectfully requests the present electronic submission not be subject to an additional filing fee.

Signature

Examiner Name	Date

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